



#13.5  
-10  
4-27-67

BOX RCE

February 4, 2002  
[Note: February 2, 2002  
was a Saturday]

Sir:

Please amend the above-identified application as follows.

RECEIVED  
FEB 26 2002  
TC 1700

Please amend claims 2, 20, 29, and 36 as follows.

2. <sup>twice</sup> (Amended) A method for manufacturing a semiconductor device comprising steps of:

forming a semiconductor film over a substrate; and

CERTIFICATE OF MAILING BY FIRST CLASS MAIL.

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231

Typed or Printed Name: Sharon Regan  
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 Person Signing Certificate